Zion For U.S. Patent Appli

14705 602045

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

,	ASMA DISPLAY DEVICE, AND MET		is sought on the invention entitle	
DISPLAY DEVI		HOD FOR MANUFACTE	RING DISPLAT MODULE OF	PLASMA
	which is attached hereto unless the follow	ing is checked:		
wa	as filed on	as Unite	d States Application Number or I	PCT International
	oplication Number		and was amended on	
	applicable).		and was afficied on	
nereby state that I l any amendment r	have reviewed and understand the content referred to above.	is of the above-identified	specification, including the clair	n(s), as amended
icknowledge the di	uty to disclose information which is materi	al to patentability as defir	ned in Title 37, Code of Federal R	egulations, § 1.56
	gn priority benefits under Title 35, United			
	e listed below and have also identified below of the application on which priority is claim		on for patent or inventor's certific	cate having a fil-
- 램.	of the application on which priority is cla	iniod.		
: I	ม11 200260	TADAN	21 Ostobon 1000	Priority Claime
(List prior	H11-299369	JAPAN	21 October, 1999	_ 🖄 Yes 🗅 No
foreign	(Number)	(Country)	(Day/Month/Year Filed)	☐ Yes ☐ No
applications. See note A	(Number)	(Country)	(Day/Month/Year Filed)	
on back of				_ 🖸 Yes 🗓 No
this page)	(Number)	(Country)	(Day/Month/Year Filed)	_ Q Yes Q No
1 <u>4</u> -8	(Number)	(Country)	(Day/Month/Year Filed)	
ee note B on back	of this page)	list for additional prior f	oreign applications	
arabu alaim tha b	enefit under Title 35, United States Code,	§ 119(e) of any United S	States provisional application(s) l	isted below.
lereby claim the o				
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icieby Claim the o	(Application Number) (Application Number)		(Filing Date)	-
	(Application Number)		(Filing Date)	_
hereby claim the b	(Application Number) enefit under Title 35, United States Code,	§ 120 of any United Sta	(Filing Date)	d, insofar as the
hereby claim the b	(Application Number) enefit under Title 35, United States Code, ch of the claims of this application is not	disclosed in the prior Uni	(Filing Date) Ites application(s) listed below an ited States application in the man	ner provided by
hereby claim the b bject matter of eac e first paragraph o	(Application Number) enefit under Title 35, United States Code, ch of the claims of this application is not of Title 35, United States Code, § 112, I ac	disclosed in the prior Uni eknowledge the duty to d	(Filing Date) Ites application(s) listed below an ited States application in the man isclose information which is mate	nner provided by erial to patentabil
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. Takashi SAITQ Full name of sole or first inventor (given name, family game)

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